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## Product Change Notification - JAON-14OICS710

**Date:** 19 Jul 2016  
**Product Category:** 16-bit Microcontrollers and Digital Signal Controllers; 8-bit Microcontrollers  
**Notification subject:** CCB 2697 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 44L QFN (8x8x0.9mm) package at MTAI assembly site.  
**Notification text:** **PCN Status:**  
Initial notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technologies available in 44L QFN (8x8x0.9mm) package at MTAI assembly site.

**Pre Change:**

Using gold (Au) bond wire

**Post Change:**

Using gold (Au) bond wire or palladium coated copper with gold flash (CuPdAu) bond wire

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	MTAI assembly site	MTAI assembly site
<b>Wire material</b>	Au wire	Au wire or CuPdAu wire
<b>Die attach material</b>	3280	3280
<b>Molding compound material</b>	G700LTD	G700LTD
<b>Lead frame material</b>	C194	C194

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve manufacturability and qualify Palladium coated copper with gold flash (CuPdAu) bond wire

**Change Implementation Status:**

In Progress

**Estimated Qualification Completion Date:  
September 2016**

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date.

**Time Table Summary:**

	July 2016				->	September 2016				
	27	28	29	30		35	36	37	38	39
Workweek										
Initial PCN Issue Date			X							
Qual Report Availability								X		
Final PCN Issue Date								X		

**Method to Identify Change:**  
Traceability code

**Qualification Plan:**  
Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan.

**Revision History:**  
**July 19, 2016:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN\\_JAON-14OICS710\\_Qual\\_Plan.pdf](#)
  - [PCN\\_JAON-14OICS710\\_Affected\\_CPN.pdf](#)
  - [PCN\\_JAON-14OICS710\\_Affected\\_CPN.xls](#)

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Affected Catalog Part Numbers (CPN)

PCN JAON-14OICS710
CATALOG_PART_NBR
DSPIC30F2023-20E/ML
DSPIC30F2023-30I/ML
DSPIC30F2023T-30I/ML
DSPIC30F2023T-30V/MLD31
DSPIC30F3010-20I/ML
DSPIC30F3010-30I/ML
DSPIC30F3010T-30I/ML
DSPIC30F3011-10I/MLB24
DSPIC30F3011-20E/ML
DSPIC30F3011-20I/ML
DSPIC30F3011-30I/ML
DSPIC30F3011T-10I/MLB21
DSPIC30F3011T-10I/MLB24
DSPIC30F3012-20E/ML
DSPIC30F3012-20I/ML
DSPIC30F3012-30I/ML
DSPIC30F3012T-20I/ML
DSPIC30F3013-20E/ML
DSPIC30F3013-20I/ML
DSPIC30F3013-30I/ML
DSPIC30F3013-30I/MLB31
DSPIC30F3013T-20I/ML
DSPIC30F3013T-30I/ML
DSPIC30F3013T-30I/MLB31
DSPIC30F3014-20E/ML
DSPIC30F3014-20I/ML
DSPIC30F3014-30I/ML
DSPIC30F3014-30I/MLA31
DSPIC30F3014T-30I/MLA31
DSPIC30F4011-20E/ML
DSPIC30F4011-20I/ML
DSPIC30F4011-30I/ML
DSPIC30F4012-20E/ML
DSPIC30F4012-20I/ML
DSPIC30F4012-30I/ML
DSPIC30F4013-20E/ML
DSPIC30F4013-20I/ML
DSPIC30F4013-30I/ML
DSPIC30F4013-30I/MLB31
DSPIC30F4013T-30I/ML
DSPIC30F4013T-30I/MLB31
PIC16F747-I/ML
PIC16F747T-I/ML

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Affected Catalog Part Numbers (CPN)

PCN JAON-14OICS710
CATALOG_PART_NBR
PIC16F777-I/ML
PIC16F777-I/ML
PIC16F874A-I/ML
PIC16F874AT-I/ML
PIC16F877A-E/ML
PIC16F877A-I/ML
PIC16F877AT-I/ML
PIC16F884-E/ML
PIC16F884-I/ML
PIC16F884T-I/ML
PIC16F887-E/ML
PIC16F887-I/ML
PIC16F887T-I/ML
PIC16F914-E/ML
PIC16F914-I/ML
PIC16F914T-I/ML
PIC16F917-E/ML
PIC16F917-I/ML
PIC16F917T-I/ML
PIC16LF777-I/ML
PIC16LF874A-I/ML
PIC16LF877A-I/ML
PIC18F4220-E/ML
PIC18F4220-I/ML
PIC18F4220T-I/ML
PIC18F4221-E/ML
PIC18F4221-I/ML
PIC18F4320-E/ML
PIC18F4320-I/ML
PIC18F4320T-I/ML
PIC18F4321-E/ML
PIC18F4321-I/ML
PIC18F4331-I/ML
PIC18F4410-I/ML
PIC18F4420-E/ML
PIC18F4420-I/ML
PIC18F4420T-I/ML
PIC18F4423-E/ML
PIC18F4423-I/ML
PIC18F4423T-I/ML
PIC18F442-I/ML
PIC18F4431-I/ML
PIC18F4450-I/ML

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Affected Catalog Part Numbers (CPN)

PCN JAON-14OICS710
CATALOG_PART_NBR
PIC18F4455-I/ML
PIC18F4458-I/ML
PIC18F4480-E/ML
PIC18F4480-I/ML
PIC18F4480T-I/ML
PIC18F4510-E/ML
PIC18F4510-I/ML
PIC18F4510T-I/ML
PIC18F4515-I/ML
PIC18F4520-E/ML
PIC18F4520-I/ML
PIC18F4520T-E/ML
PIC18F4520T-I/ML
PIC18F4523-E/ML
PIC18F4523-I/ML
PIC18F4523T-I/ML
PIC18F4525-E/ML
PIC18F4525-I/ML
PIC18F4525T-I/ML
PIC18F452-E/ML
PIC18F452-I/ML
PIC18F452T-I/ML
PIC18F4550-I/ML
PIC18F4553-I/ML
PIC18F4580-E/ML
PIC18F4580-I/ML
PIC18F4580T-I/ML
PIC18F4585-E/ML
PIC18F4585-H/ML
PIC18F4585-I/ML
PIC18F4585-I/MLC01
PIC18F4585T-I/ML
PIC18F4610-I/ML
PIC18F4620-E/ML
PIC18F4620-I/ML
PIC18F4620T-I/ML
PIC18F4680-E/ML
PIC18F4680-H/ML
PIC18F4680-I/ML
PIC18F4680T-I/ML
PIC18F4682-E/ML
PIC18F4682-I/ML
PIC18F4685-E/ML

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Affected Catalog Part Numbers (CPN)

PCN JAON-14OICS710
CATALOG_PART_NBR
PIC18F4685-I/ML
PIC18F4685T-I/ML
PIC18LF4220-I/ML
PIC18LF4220T-I/ML
PIC18LF4221-I/ML
PIC18LF4221T-I/ML
PIC18LF4320-I/ML
PIC18LF4320T-I/ML
PIC18LF4320T-I/MLC06
PIC18LF4321-I/ML
PIC18LF4331-I/ML
PIC18LF4410-I/ML
PIC18LF4420-I/ML
PIC18LF4420T-I/ML
PIC18LF4423-I/ML
PIC18LF4423T-I/ML
PIC18LF442-I/ML
PIC18LF442T-I/ML
PIC18LF4431-I/ML
PIC18LF4450-I/ML
PIC18LF4450T-I/ML
PIC18LF4455-I/ML
PIC18LF4458-I/ML
PIC18LF4480-I/ML
PIC18LF4480T-I/ML
PIC18LF4510-I/ML
PIC18LF4510T-I/ML
PIC18LF4515-I/ML
PIC18LF4520-I/ML
PIC18LF4520T-I/ML
PIC18LF4523-I/ML
PIC18LF4523T-I/ML
PIC18LF4525-I/ML
PIC18LF4525T-I/ML
PIC18LF452-I/ML
PIC18LF452T-I/ML
PIC18LF4539-I/ML
PIC18LF4550-I/ML
PIC18LF4553-I/ML
PIC18LF4580-I/ML
PIC18LF4585-I/ML
PIC18LF4585T-I/ML
PIC18LF4610-I/ML

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Affected Catalog Part Numbers (CPN)

PCN JAON-14OICS710
CATALOG_PART_NBR
PIC18LF4620-I/ML
PIC18LF4620-I/ML035
PIC18LF4620T-I/ML
PIC18LF4620T-I/ML035
PIC18LF4680-I/ML
PIC18LF4682-I/ML
PIC18LF4685-I/ML
PIC18LF4685T-I/ML